

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
Name		Execution Date
Reza Argenty Pagaila		07/28/2008
Byung Tai Do		07/28/2008
Dioscoro A. Merilo		07/28/2008
RECEIVING PARTY DATA		
Name:	STATS ChipPAC Ltd.	
Street Address:	10 Ang Mo Kio Street 65	
Internal Address:	Techpoint #05-17/20	
City:	Singapore	
State/Country:	SINGAPORE	
Postal Code:	569059	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	12182132	
CORRESPONDENCE DATA		
Fax Number:	(408)738-0881	
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>		
Phone:	408-738-0592	
Email:	efiling@ishimarulaw.com	
Correspondent Name:	LAW OFFICES OF MIKIO ISHIMARU	
Address Line 1:	333 W. EL CAMINO REAL	
Address Line 2:	SUITE 330	
Address Line 4:	SUNNYVALE, CALIFORNIA 94087	
ATTORNEY DOCKET NUMBER:	27-536	
NAME OF SUBMITTER:	Mikio Ishimaru	
Total Attachments: 3		

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PATENT
REEL: 021368 FRAME: 0006

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PATENT

REEL: 021368 FRAME: 0007

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

RDL PATTERNING WITH PACKAGE ON PACKAGE SYSTEM

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, Republic of Singapore (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

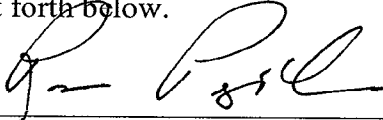
NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.
3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

5. Said Assignor(s) hereby authorize and request the attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

Serial Number: 12/182,132 Filing Date: July 30, 2008

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



Reza Argenty Pagaila

28 July - 2008

Date



Witness Signature

CHUA PEI EE LINDA

Print Witness Name

28 July 2008

Date



Witness Signature

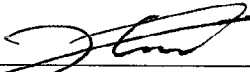
JOSE ALVIN CAPARAS

Print Witness Name

28 July 2008

Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



Byung Tai Do

July 28, 2008

Date



Witness Signature

CHUA PEI EE LINDA

Print Witness Name

28 July 2008

Date



Witness Signature

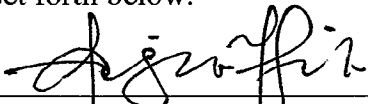
JOSE ALVIN CAPARAS

Print Witness Name

28 July 2008

Date


IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



Dioscoro A. Merilo

JULY 28, 2008

Date



Witness Signature

CHUA FEL EE LINDA

Print Witness Name

28 July 2008

Date



Witness Signature

JOE AWIN CAPARAS

Print Witness Name

28 July 2008

Date